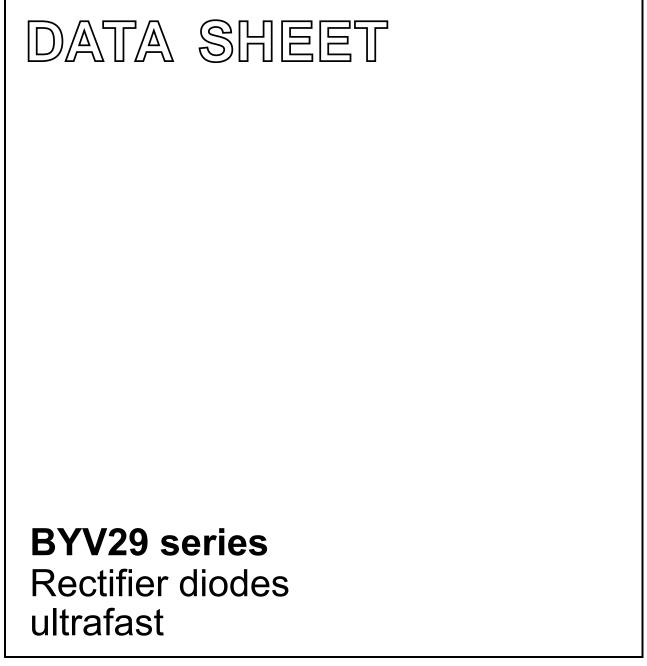
DISCRETE SEMICONDUCTORS



Product specification

September 1998



### **Product specification**

**BYV29** series

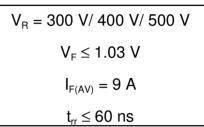
### **Rectifier diodes** ultrafast

### **FEATURES**

- · Low forward volt drop
- · Fast switching
- · Soft recovery characteristic
- High thermal cycling performance
- · Low thermal resistance

# **SYMBOL** k а 2 1

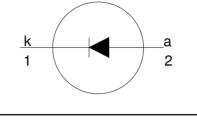
### QUICK REFERENCE DATA



### **GENERAL DESCRIPTION**

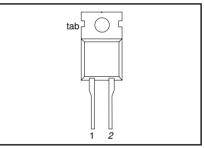
Ultra-fast, epitaxial rectifier diodes intended for use as output rectifiers in high frequency switched mode power supplies.

The BYV29 series is supplied in the conventional leaded SOD59 (TO220AC) package.



DESCRIPTION

### SOD59 (TO220AC)



### LIMITING VALUES

Limiting values in accordance with the Absolute Maximum System (IEC 134).

PINNING

PIN

1

2

tab

cathode

anode

cathode

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.		UNIT	
V <sub>RRM</sub> V <sub>RWM</sub> V <sub>B</sub>	Peak repetitive reverse voltage Crest working reverse voltage Continuous reverse voltage	BYV29	- - -	<b>-300</b> 300 300 300	<b>-400</b> 400 400 400	<b>-500</b> 500 500 500	V V V
I <sub>F(AV)</sub>	Average forward current <sup>1</sup>	square wave; $\delta$ = 0.5; T <sub>mb</sub> $\leq$ 123 °C	-		9	-	Α
I <sub>FRM</sub>	Repetitive peak forward current	$t = 25 \mu s; \delta = 0.5;$ $T_{mb} \le 123 ^{\circ}C$	-		18		А
I <sub>FSM</sub>	Non-repetitive peak forward current.	t = 10 ms t = 8.3 ms sinusoidal; with reapplied	-		100 110		A A
T <sub>stg</sub> T <sub>i</sub>	Storage temperature Operating junction temperature	V <sub>RRM(max)</sub>	-40 -		150 150		°C °C

### THERMAL RESISTANCES

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
R <sub>th j-mb</sub>	Thermal resistance junction to mounting base		-	-	2.5	K/W
R <sub>th j-a</sub>	Thermal resistance junction to ambient	in free air.	-	60	-	K/W

<sup>1</sup> Neglecting switching and reverse current losses.

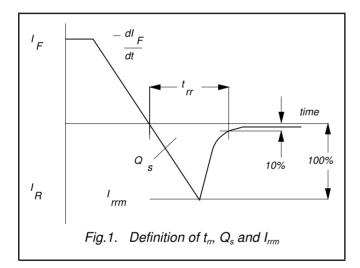
# Rectifier diodes ultrafast

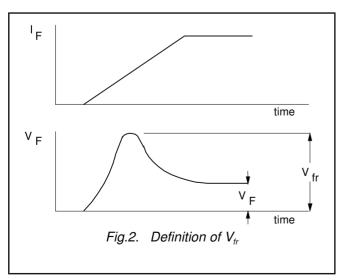
# BYV29 series

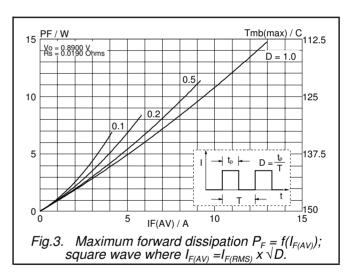
### **ELECTRICAL CHARACTERISTICS**

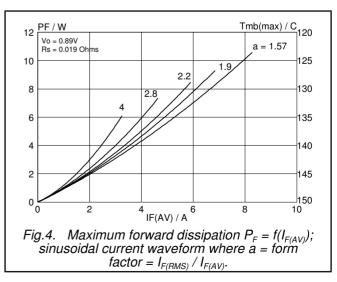
 $T_i = 25$  °C unless otherwise stated

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>F</sub>	Forward voltage	I <sub>F</sub> = 8 A; T <sub>i</sub> = 150°C	-	0.90	1.03	V
	_	$I_F = 8 A$	-	1.05	1.25	V
		$I_{\rm F} = 20  {\rm A}$	-	1.20	1.40	V
I <sub>R</sub>	Reverse current	$V_{\rm R} = V_{\rm RRM}$	-	2.0	50	μA
		$V_R^{T} = V_{RRM}^{T}; T_j = 100 \degree C$ $I_F = 2 \ A \ to \ V_R \ge 30 \ V;$	-	0.1	0.35	mΑ
Qs	Reverse recovery charge	$I_{\rm F} = 2 {\rm A}$ to $V_{\rm B}^{\prime} \ge 30 {\rm V};$	-	40	60	nC
-		$dI_{F}/dt = 20 A/\mu s$				
t <sub>rr</sub>	Reverse recovery time	$I_F = 1 \text{ A to } V_R \ge 30 \text{ V};$	-	50	60	ns
	-	$dI_F/dt = 100 \text{ Å}/\mu \text{s}$				
l <sub>rrm</sub>	Peak reverse recovery current	$I_{\rm F} = 10 \text{ A to } V_{\rm B} \ge 30 \text{ V};$	-	4.0	5.5	A
		$dI_{F}/dt = 50 A/\mu s; T_{i} = 100^{\circ}C$				
V <sub>fr</sub>	Forward recovery voltage	I <sub>F</sub> = 10 A; dI <sub>F</sub> /dt = 10 A/μs	-	2.5	-	V



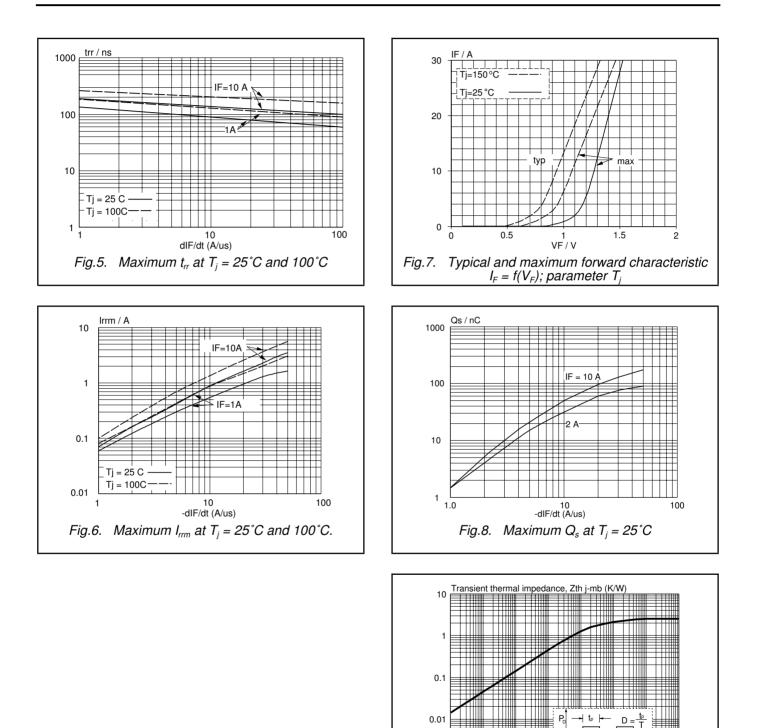






**BYV29** series

# Rectifier diodes ultrafast



Π.

100ms

1s

10s

10ms

0.001 └─ 1us

10us

100us

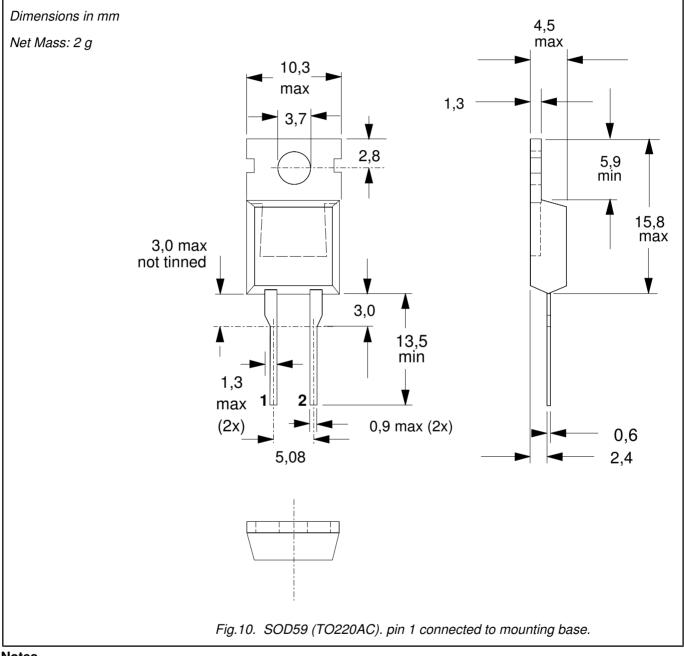
1ms

pulse width, tp (s) Fig.9. Transient thermal impedance  $Z_{th j,mb} = f(t_p)$ 

### **Rectifier diodes** ultrafast

# **BYV29** series

# **MECHANICAL DATA**



Notes

Refer to mounting instructions for TO220 envelopes.
Epoxy meets UL94 V0 at 1/8".

# Legal information

### DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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#### **Contact information**

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